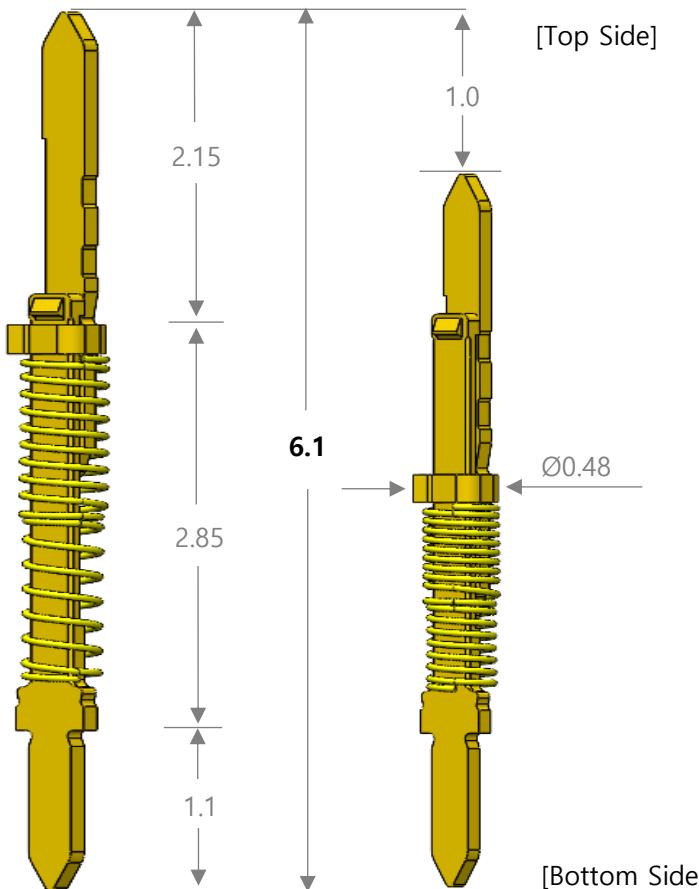


# 1. Products – 1) Stamped Probe Pin

## Application

- LGA , Interposer
- 0.8P , 1.0P , 1.27P



## Mechanical Spec.

Recommended Travel	10.0 gf±12% @ 1.00mm
Full Travel	14.5 gf±12% @ 1.30mm
Temperature	-40 °C ~ 150 °C

## Material & Plating

Part	Material	Plating
Top/Bottom Plunger	Hardened BeCu	Ni, Au Plated
Spring	Stainless Steel	Ni, Au Plated

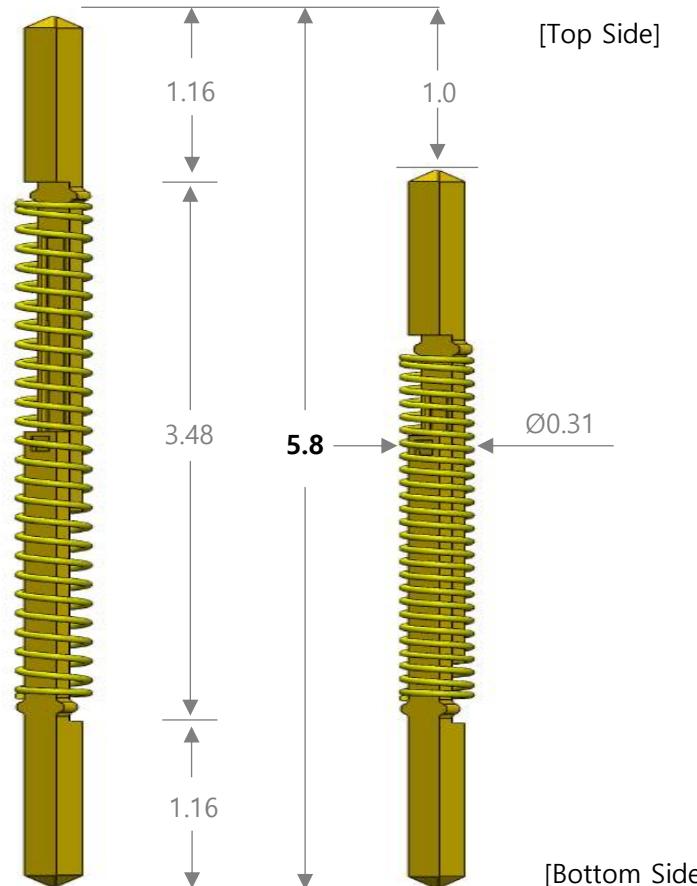
## Electrical Spec.

Current Rating	3A Continuous
Resistance	> 100mΩ
Insertion Loss	12.35GHz @ -1dB
Return Loss	8.47GHz @ -20dB

# 1. Products – 1) Stamped Probe Pin

## Application

- LGA , Interposer
- 0.5P Over



## Mechanical Spec.

Recommended Travel	7.0 gf±10% @ 1.00mm
Full Travel	10.0 gf±10% @ 1.35mm
Temperature	-40 °C ~ 150 °C

## Material & Plating

Part	Material	Plating
Top/Bottom Plunger	Hardened BeCu	Ni, Au Plated
Spring	Stainless Steel	Ni, Au Plated

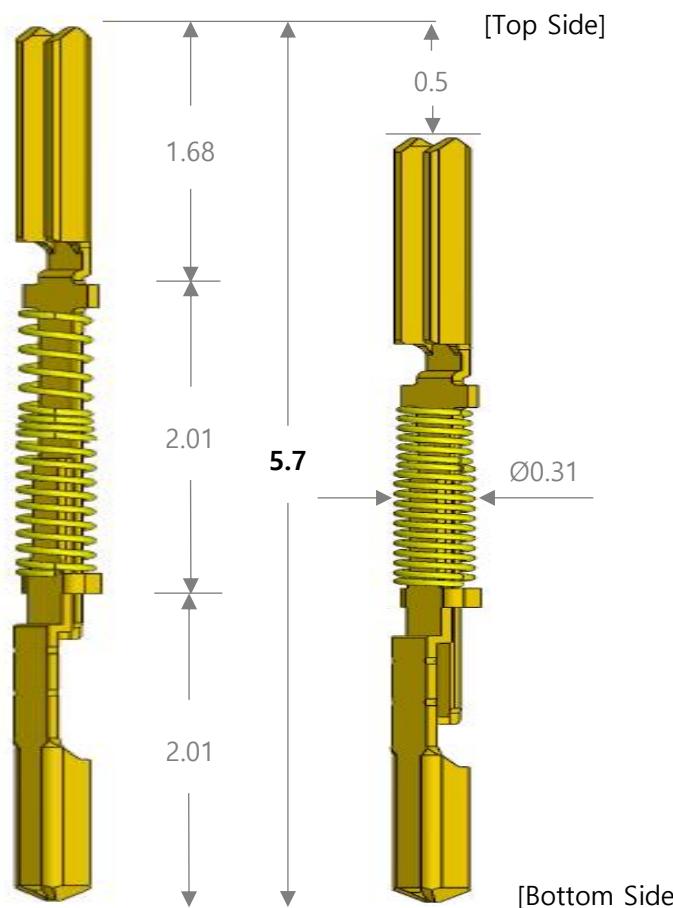
## Electrical Spec.

Current Rating	3A Continuous
Resistance	≤150mΩ
Insertion Loss	10.04GHz @ -1dB
Return Loss	7.86GHz @ -20dB

# 1. Products – 1) Stamped Probe Pin

## Application

- BGA , LGA , QFP , TSOP
- 0.4P Over



## Mechanical Spec.

Recommended Travel	15.0 gf±10% @ 0.50mm
Full Travel	18.0 gf±10% @ 0.60mm
Temperature	-40 °C ~ 150 °C

## Material & Plating

Part	Material	Plating
Top/Bottom Plunger	Hardened BeCu	Ni, Au Plated
Spring	Stainless Steel	Ni, Au Plated

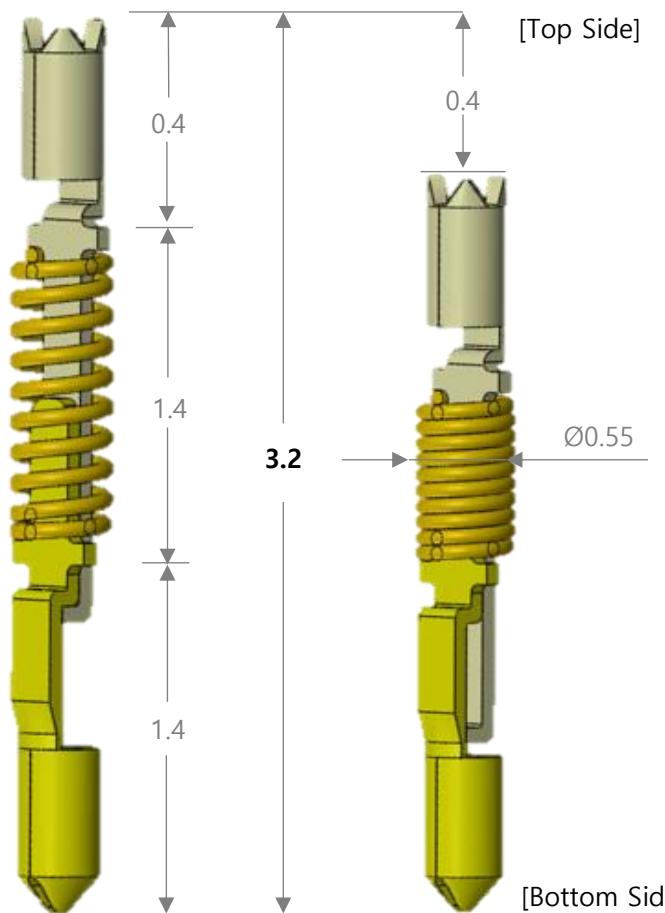
## Electrical Spec.

Current Rating	3A Continuous
Resistance	≤100mΩ
Insertion Loss	9.70GHz @ -1dB
Return Loss	4.84GHz @ -20dB

# 1. Products – 1) Stamped Probe Pin

## Application

- BGA , LGA , QFP , QFN , TSOP
- 0.8P , 1.0P , 1.27P



## Mechanical Spec.

Recommended Travel	20.0 gf±10% @ 0.40mm
Full Travel	25.0 gf±10% @ 0.55mm
Temperature	-40 °C ~ 150 °C

## Material & Plating

Part	Material	Plating
Top/Bottom Plunger	Hardened BeCu	Ni, Au Plated
Spring	Stainless Steel	Ni, Au Plated

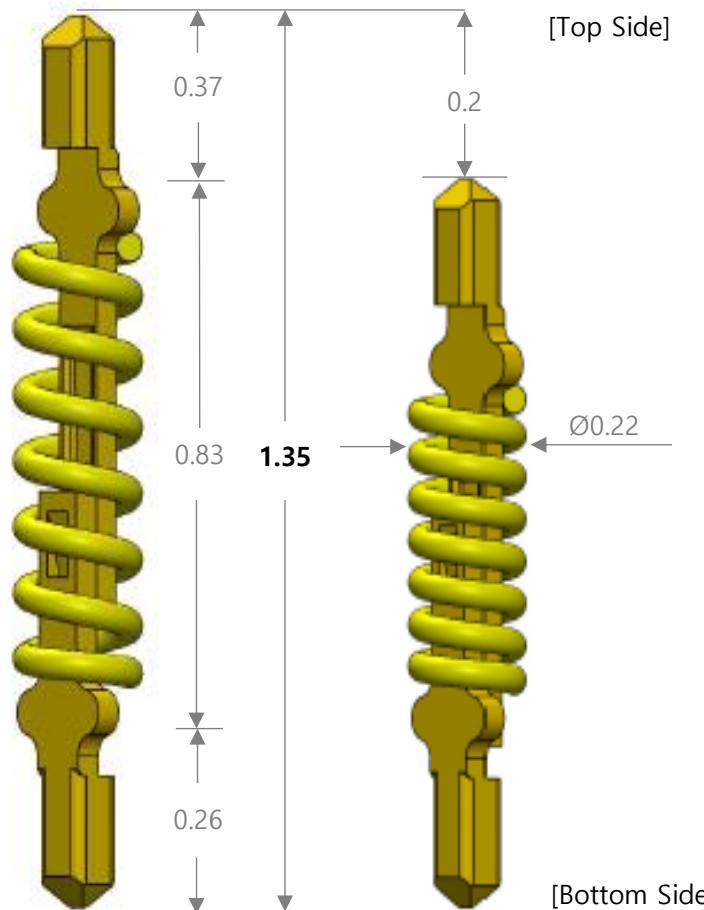
## Electrical Spec.

Current Rating	3A Continuous
Resistance	≤100mΩ
Insertion Loss	31.37GHz @ -1dB
Return Loss	12.66GHz @ -20dB

# 1. Products – 1) Stamped Probe Pin

## Application

- BGA , LGA , QFP , QFN , TSOP
- 0.3P



## Mechanical Spec.

Recommended Travel	20.0 gf±10% @ 0.20mm
Full Travel	25.0 gf±10% @ 0.25mm
Temperature	-40 °C ~ 150 °C

## Material & Plating

Part	Material	Plating
Top/Bottom Plunger	Hardened BeCu	Ni, Au Plated
Spring	Stainless Steel	Ni, Au Plated

## Electrical Spec.

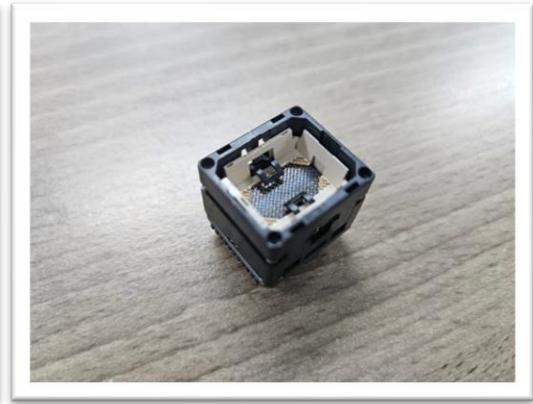
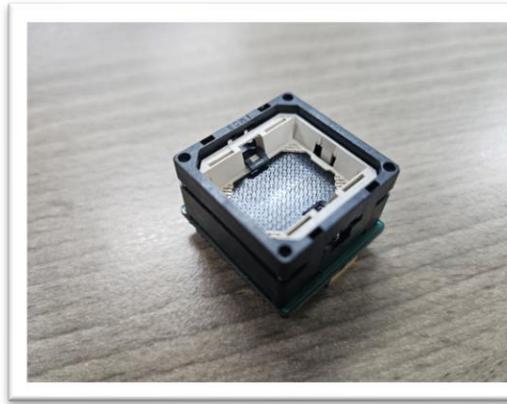
Current Rating	2A Continuous
Resistance	≤100mΩ
Insertion Loss	35.01GHz @ -1dB
Return Loss	19.16GHz @ -20dB

# 1. Products – 2) Test & Burn-in Socket



Clam Shell Type

Rotary Type



Heat Sink Type

Open Top Type

# 1. Products – 2) Test Socket

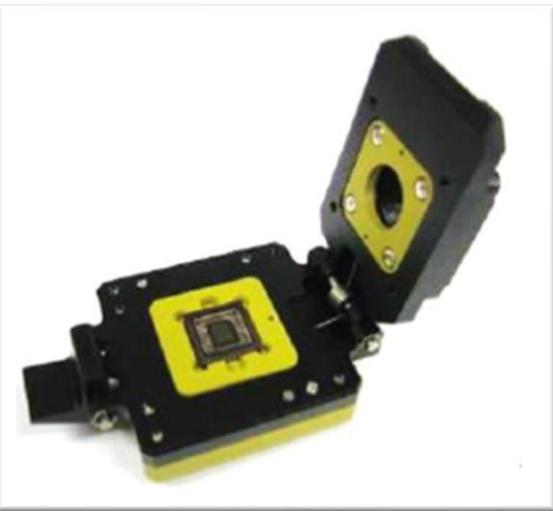
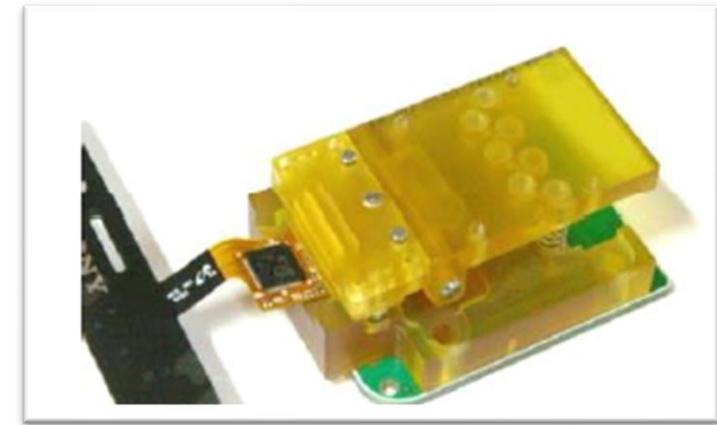


Image Sensor



Pin Block



Clamp Type



FPCB Test JIG

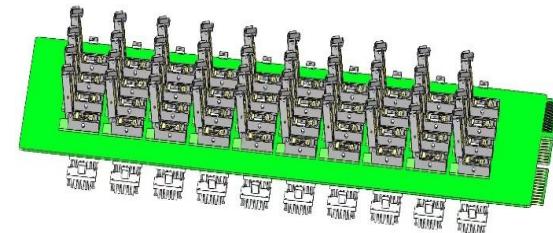
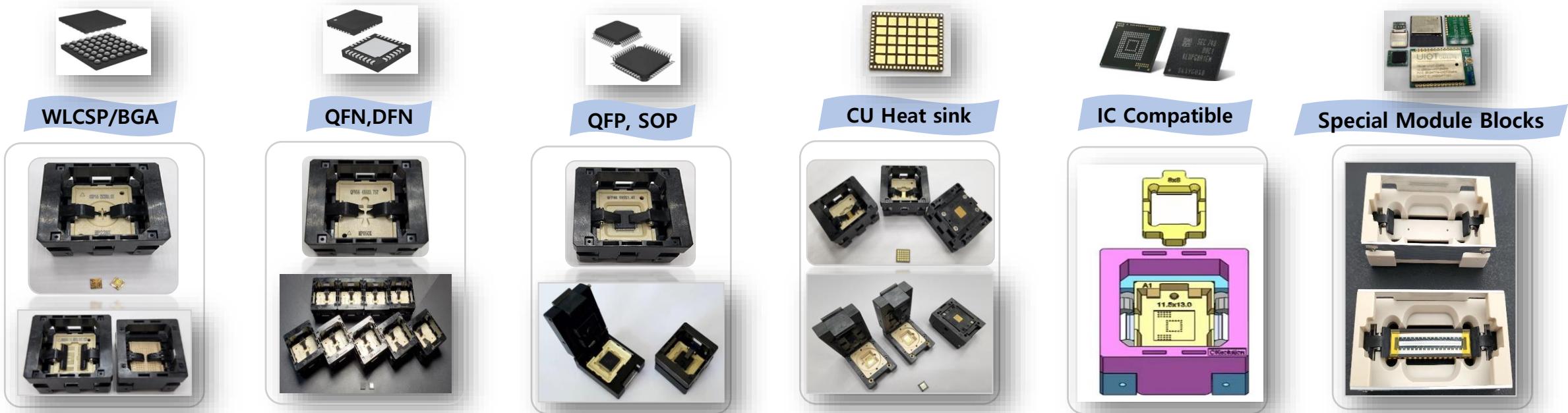


Air Cylinder Type



Dead Bug Socket

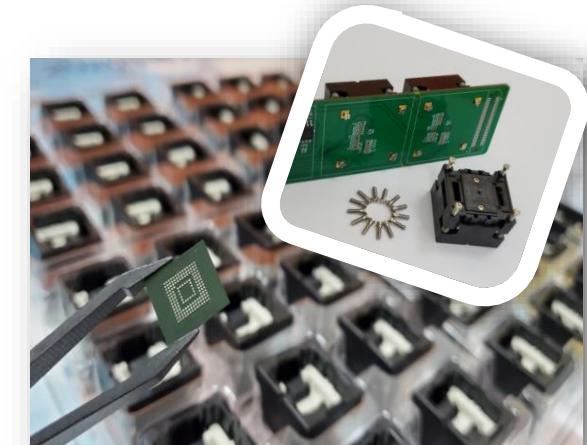
# 1. Products - 2) Test Socket



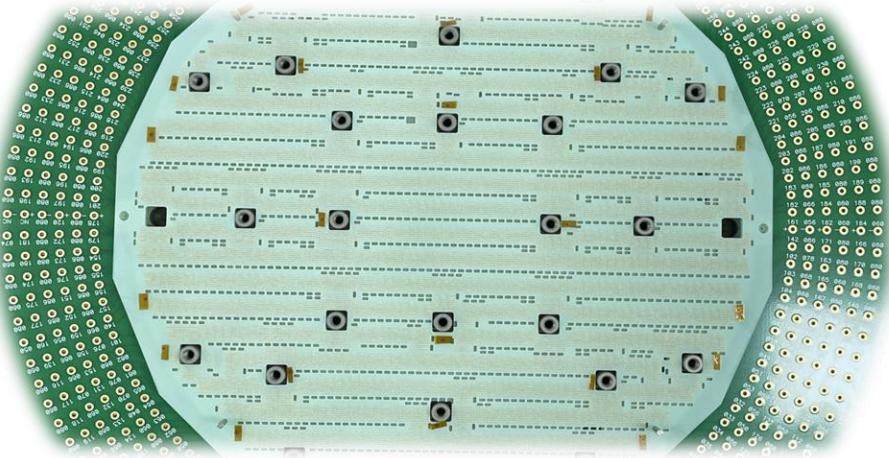
## 1. Products - 2) Test Socket



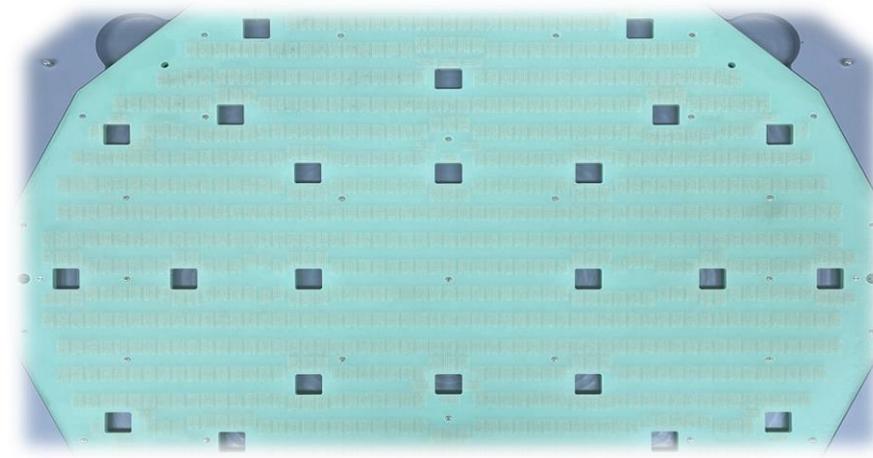
- ① **Lead Time in 20 days**
- ② **Cost-efficient socket**
- ③ **Coverage anyone IC Package**
- ④ **Applied high performance Probe Pin in Socket**
- ⑤ **Socket size : 26x26, 28x32**



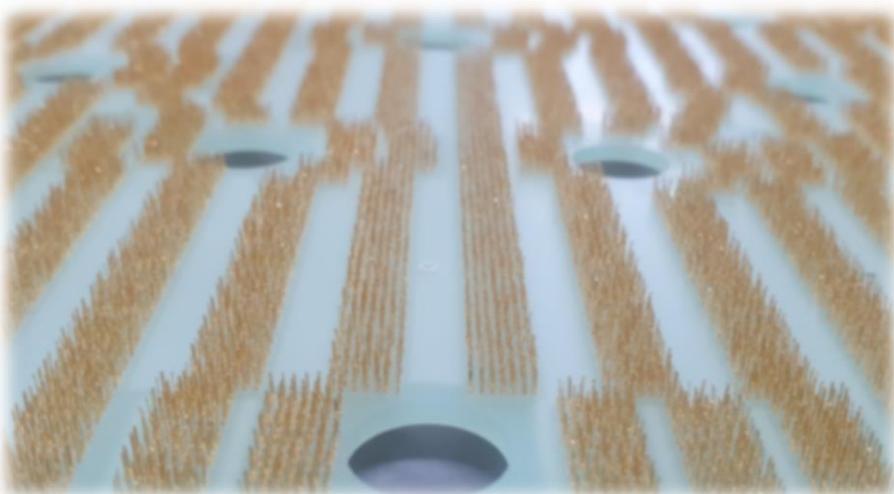
# 1. Products – 3) Interposer



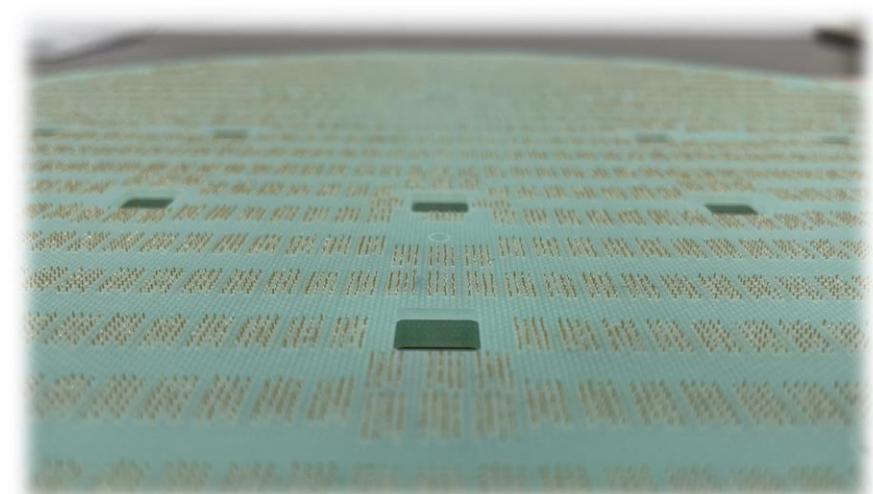
Interposer on Test Board



Interposer

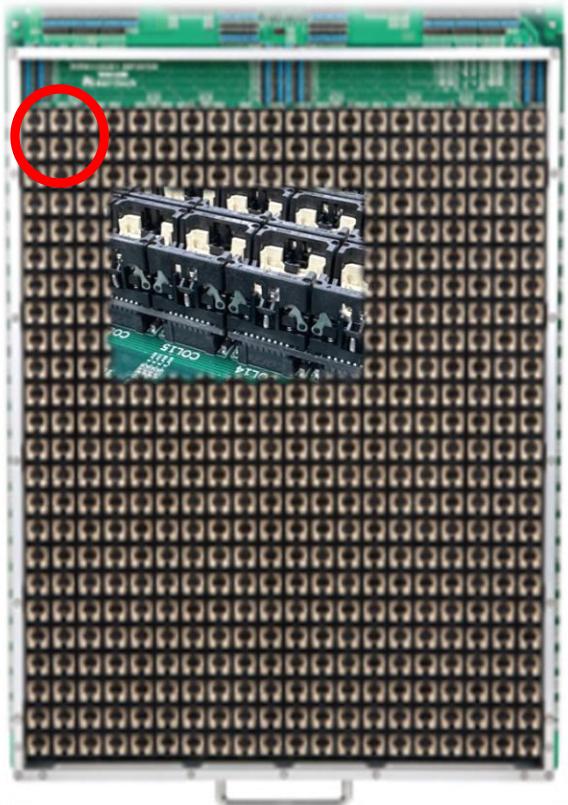


Interposer

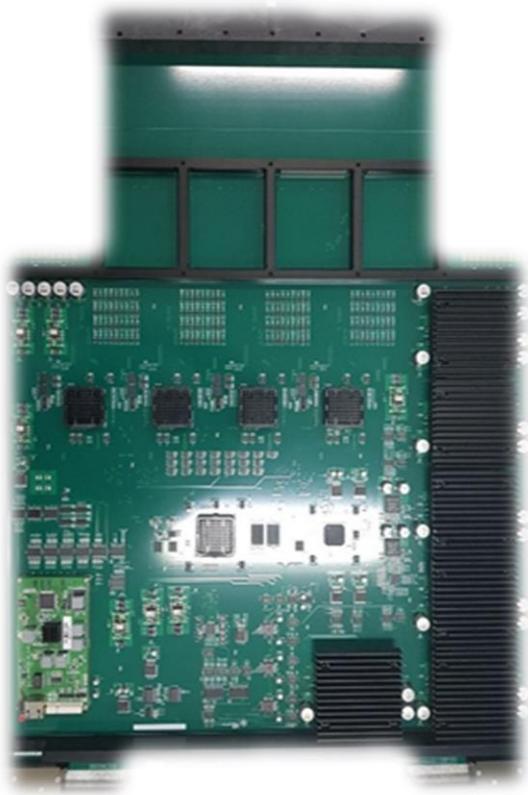


Interposer

# 1. Products – 4) Test & Burn-in Board



Burn-In Board



System Board

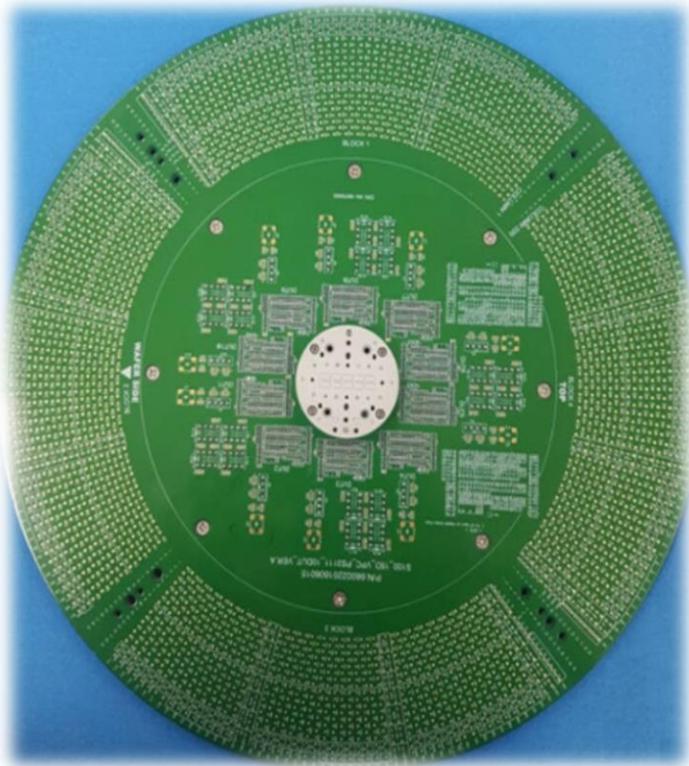


Logic BIB



HAST Board

# 1. Products – 5) SMT & Assembly



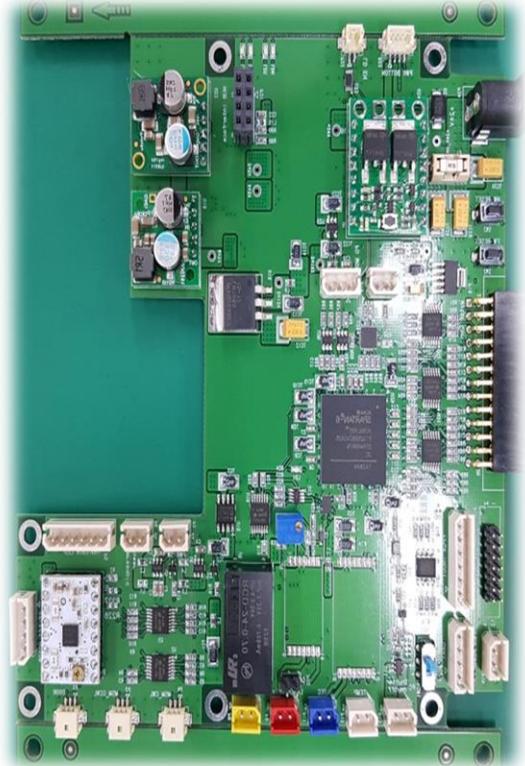
Probe Card



LCD System Board

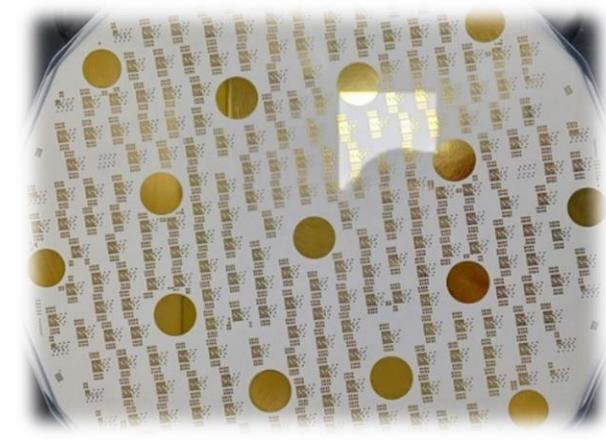
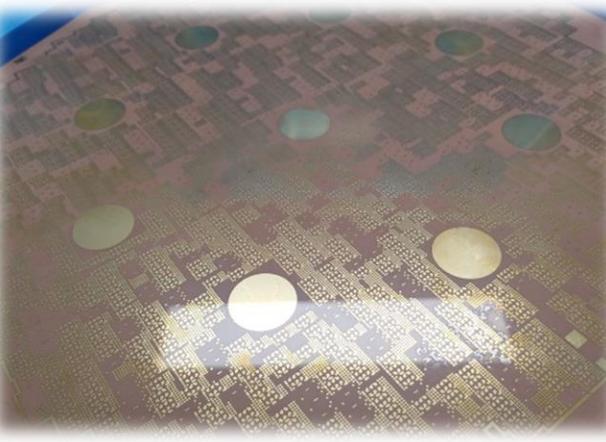
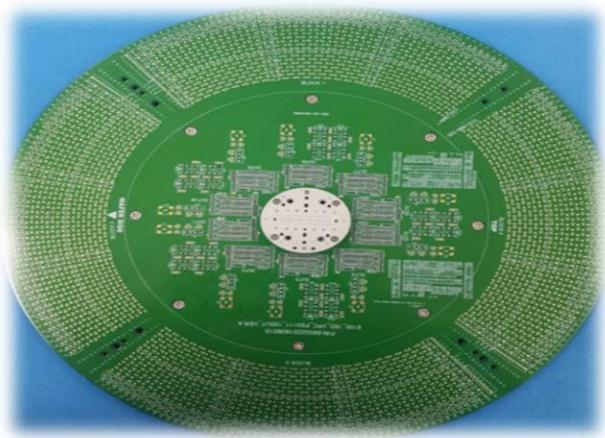
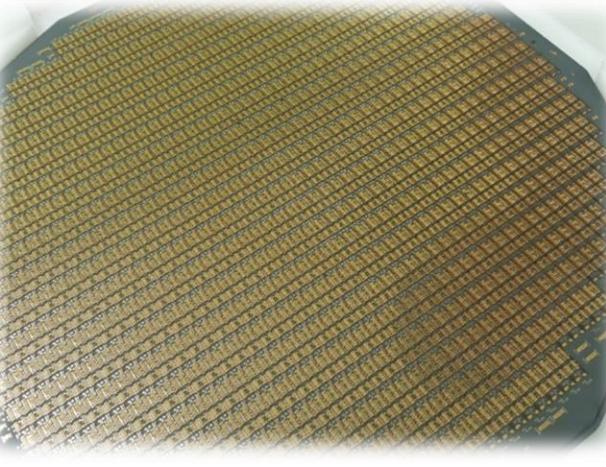
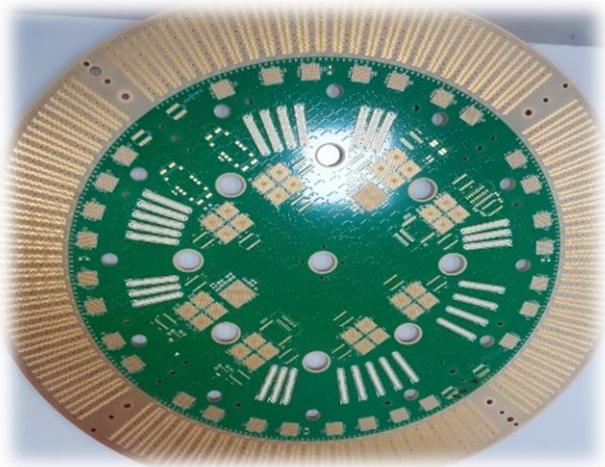


Fan Controller



Tester Board

# 1. Products - 5) SMT & Assembly



Probe Card

# 1. Products – 6) Fixture & Jig



Ass'y Jig



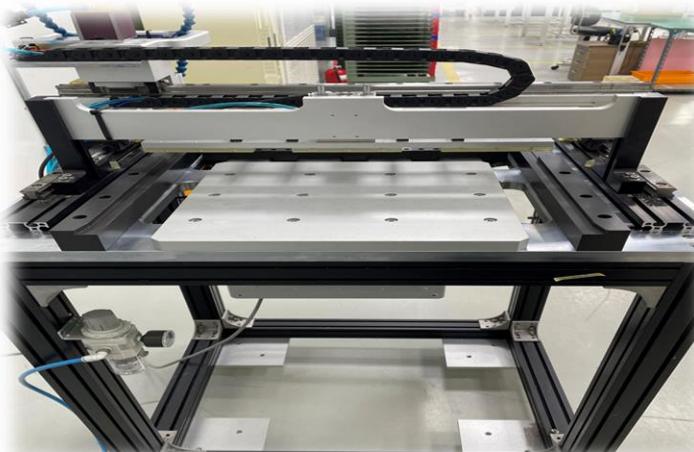
Test Jig



Test Board Frame



Test Board Frame



Cutting Jig



Rack Case

## 2. Equipment



Maker	FANUC' Robodrill Series ( $\alpha$ -D21MiB5)
Dimension (X x Y x Z)	500 x 400 x 330 (mm)
RPM	10,000 ~ 24,000 (r/min)
Material	Torlon, Peek, Ceramic Peek, Ultem
Application	Precision Machining Hole
Q'ty	16
Product	Test Socket, Module Socket, RF Socket

### 3. Production Line



FANUC's Robodrill

### 3. Production Line

SMT Line



Rework Station



Retouch Line



Cleaning Room



TEST Line



### 3. Production Line

Wave Solder



Bonding Line



Selective Solder



Insert Line



Application Line



Assembly



## 4. Inspection Line

X-Ray Inspector



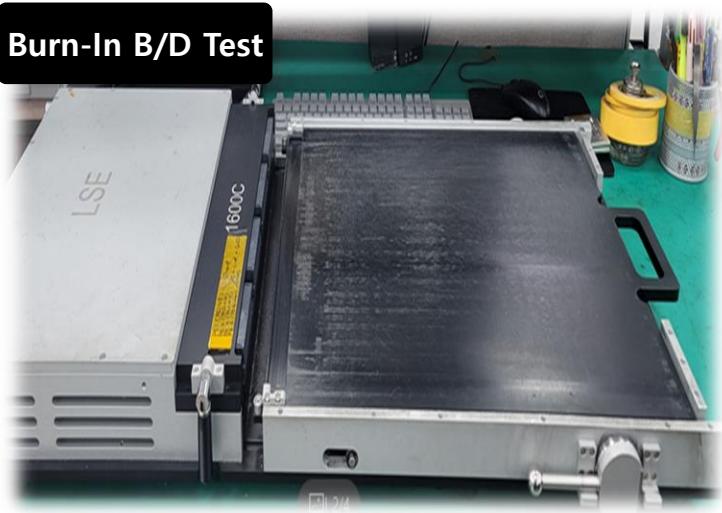
Vision Inspection



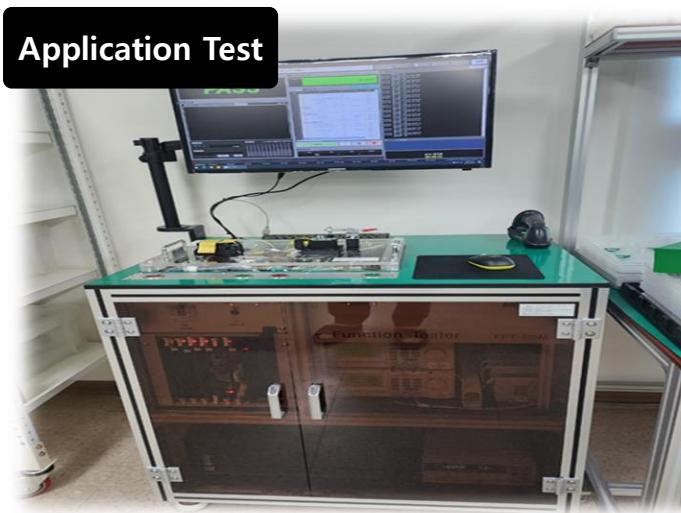
Auto BBT Test



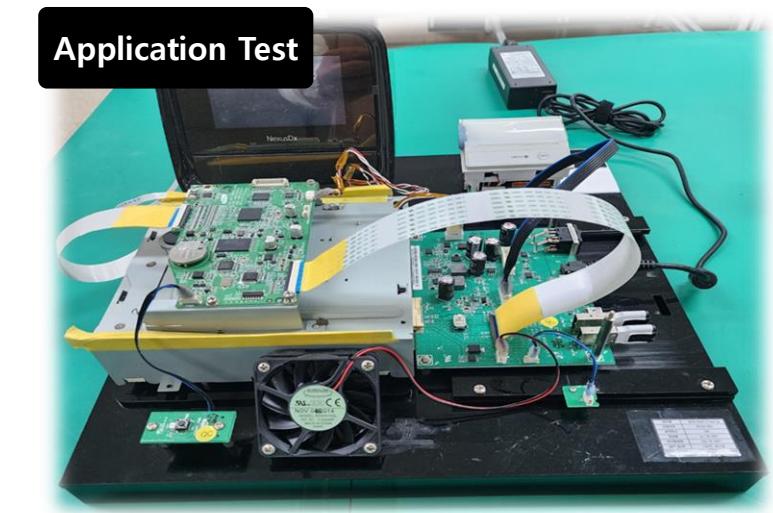
Burn-In B/D Test



Application Test



Application Test



# 4. Inspection Line

Visual Inspection Room



Vision Inspection



Automated Visual Inspection



Global 2D Inspection



Zeiss 2D Inspection



Microscope

